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PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10075566	FILING DATE 02/13/2002	CLASS 134	SUBCLASS 003	GAU 1746	EXAMINER CHAUDHRY
<b>**APPLICANTS:</b> Aoki Hidemitsu; Yamasaki Shinya;					
<p><b>BEST AVAILABLE COPY</b></p>					
<b>**CONTINUING DATA VERIFIED:</b> THIS APPLICATION IS A DIV OF 09/313,027 05/17/1999					
<b>** FOREIGN APPLICATIONS VERIFIED:</b> JAPAN 10-138365 05/20/1998					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials		ATTORNEY DOCKET NO 12688A			
TITLE : Method for cleaning semiconductor wafer after chemical mechanical polishing on copper wiring <small>U.S. DEPT. OF COMM./PAT. &amp; TM.-PTO-435L (Rev. 12-94)</small>					

<b>NOTICE OF ALLOWANCE MAILED</b>		<b>CLAIMS ALLOWED</b>	
		Assistant Examiner	
<b>ISSUE FEE</b>		Total Claims	
Amount Due	Date Paid	Print Claim for O.G.	
		<b>DRAWING</b>	
		Sheets Drwg.	Figs. Drwg.
		Print Fig.	
<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>		Primary Examiner	
		Application Examiner	
		<b>PREPARED FOR ISSUE</b>	
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